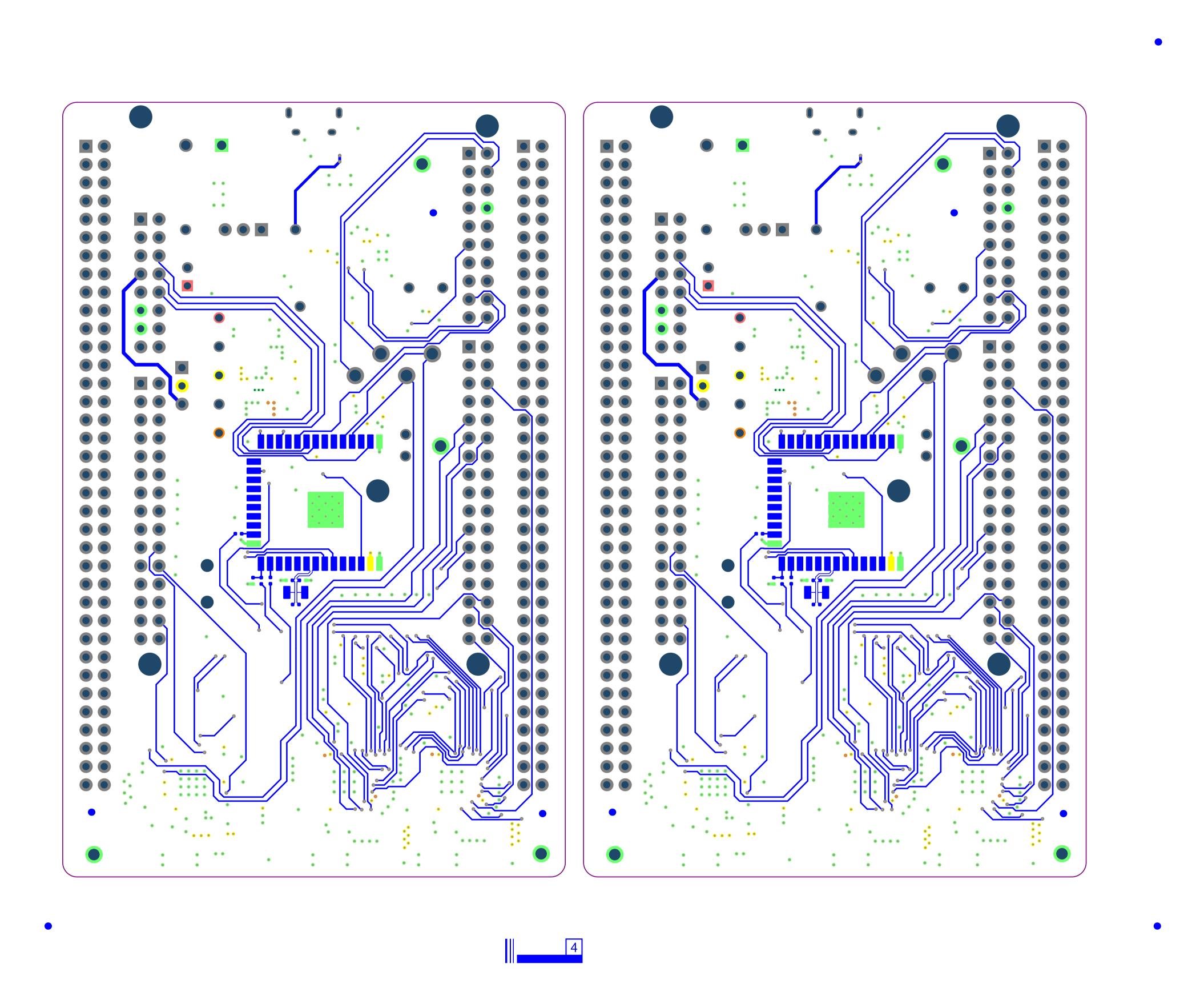


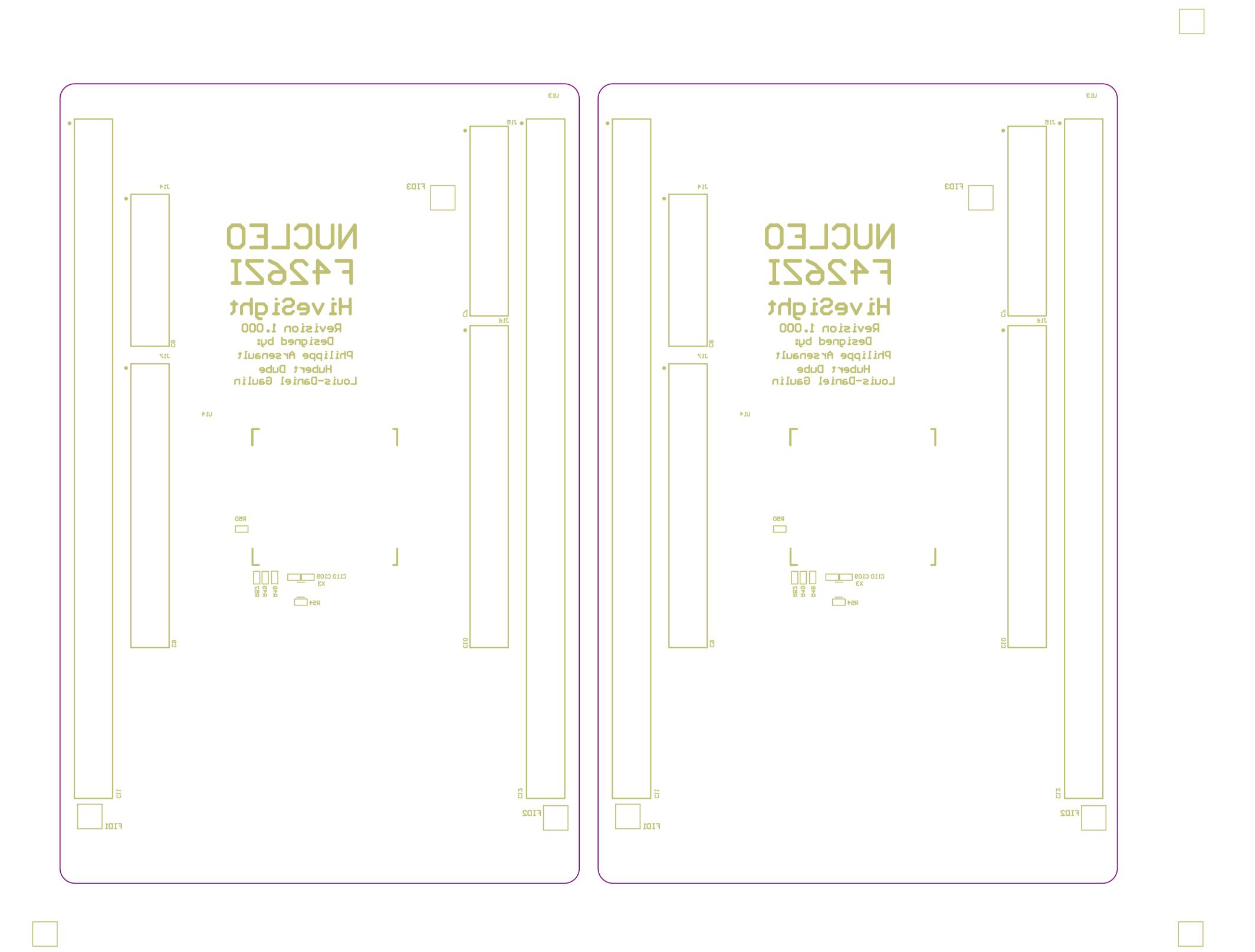
LAVED 1. TOP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	O.39mil	3.5	
1	Тор	Copper	1.38mil		
	Dielectric 1	PP-006	4.80mil	4.2	
2	GND	Copper	1.38mil		
	Dielectric 2	Core-009	45.28mil	4.2	
3	PWR	Copper	1.38mil		
	Dielectric 3	PP-006	4.80mil	4.2	
4	Bottom	Copper	1.38mil		
	Bottom Solder	Solder Resist	O.39mil	3.5	
	Bottom Overlay				
	///////////////////////////////////////	///////////////////////////////////////			///////////////////////////////////////

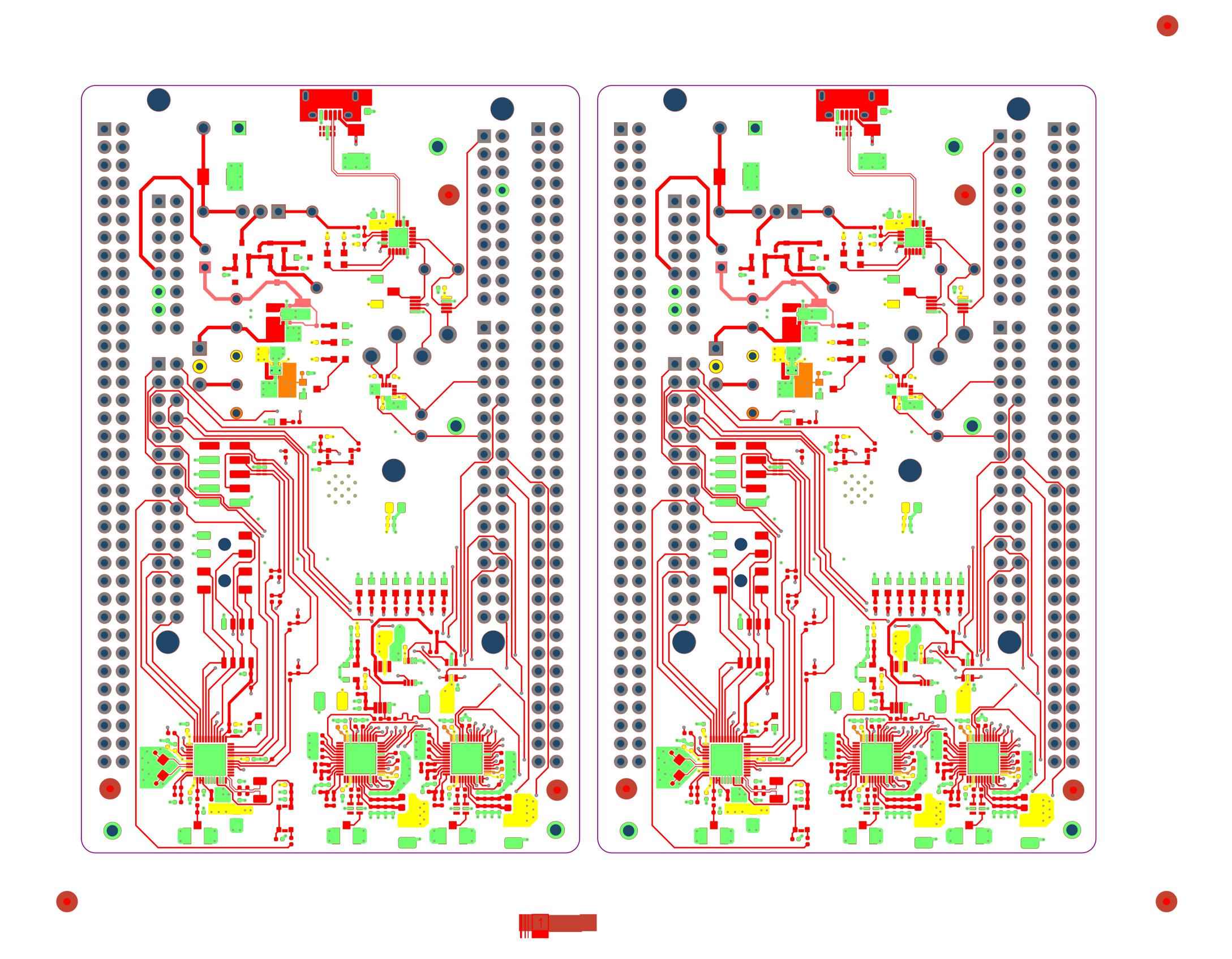


LAYER 4: BOTTOM

 TOP SILKSCREEN

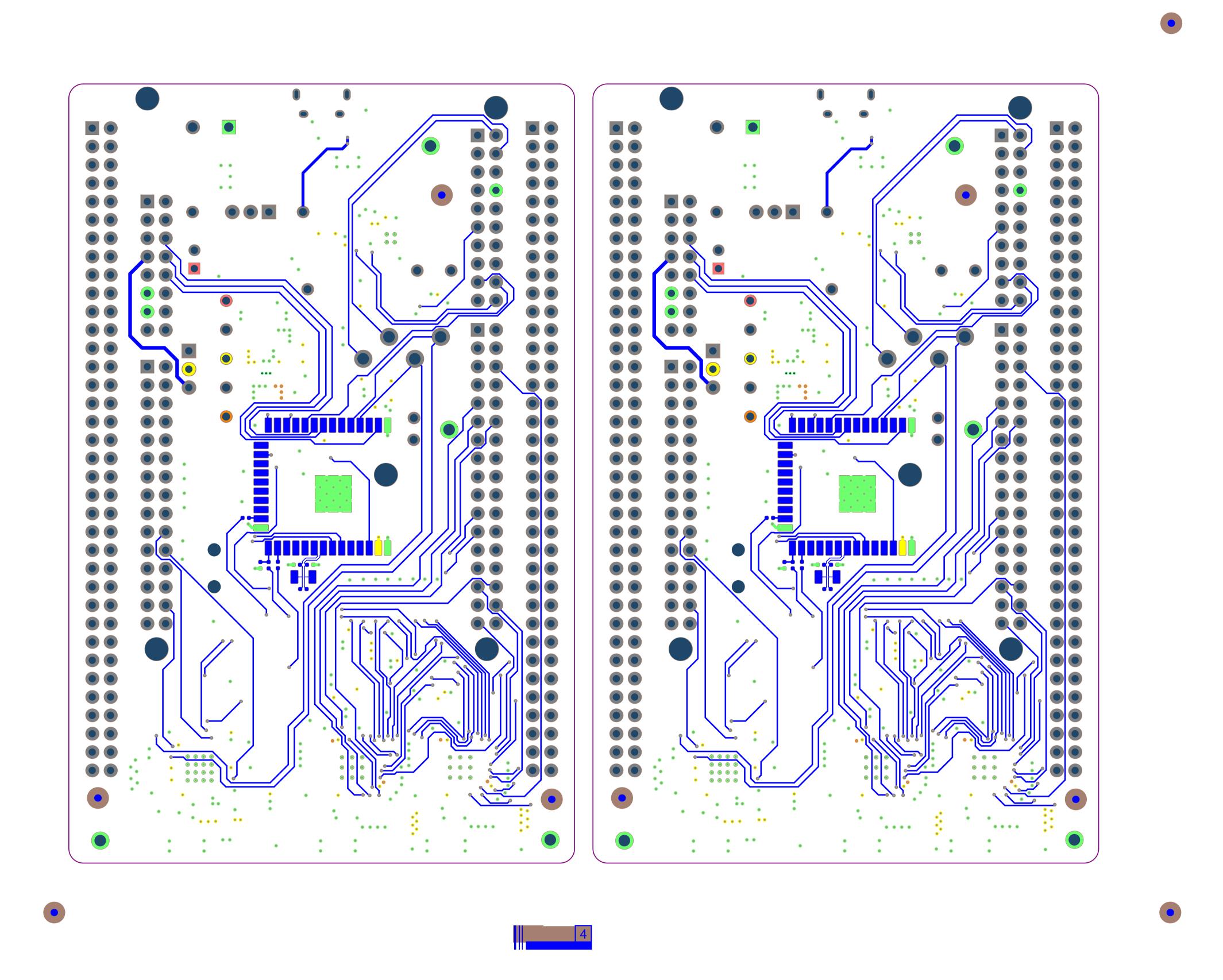


BOTTOM SILKSCREEN BOARD OUTLINE



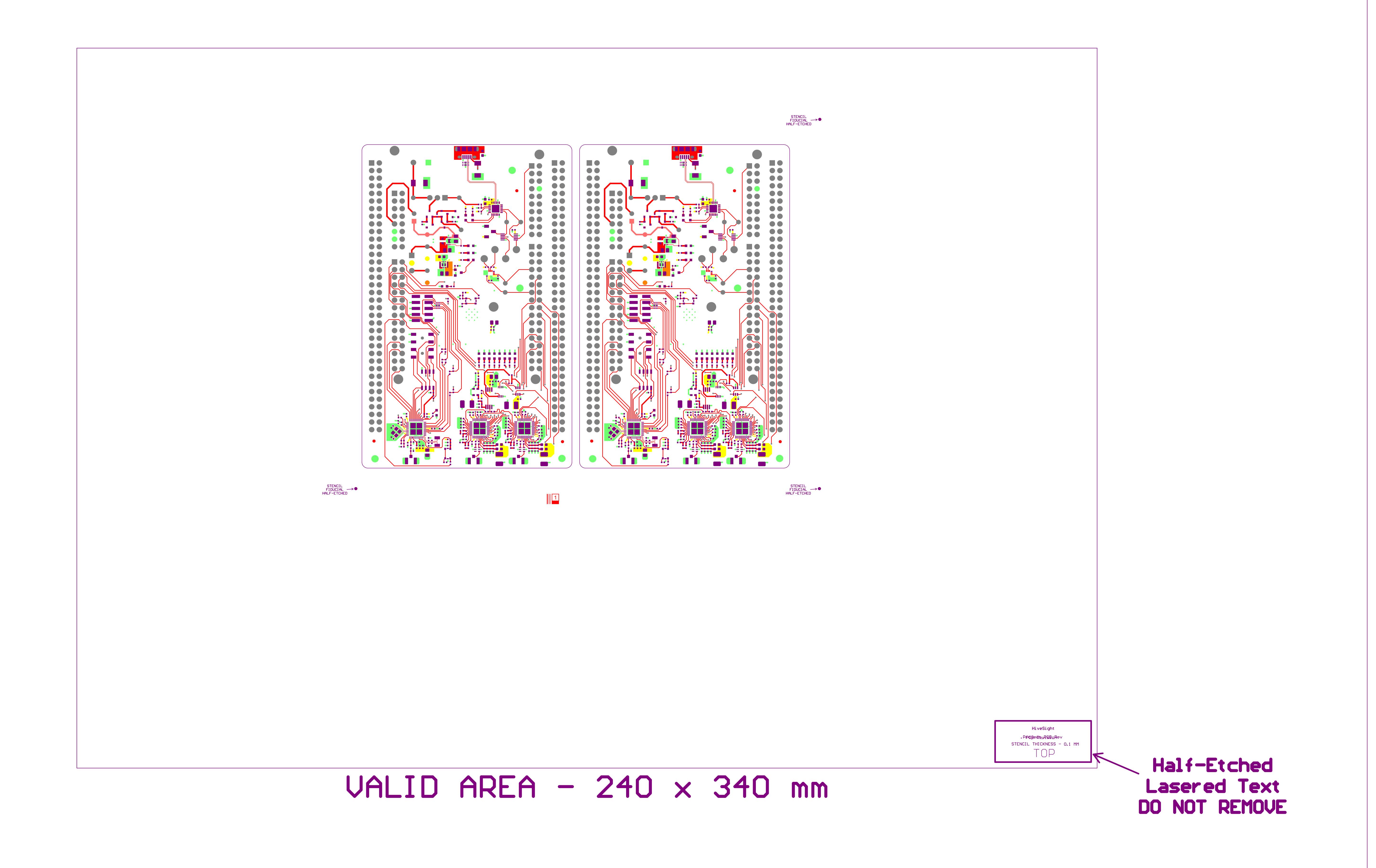
TOP SOLDERMASK LAYER 1: TOP

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	O.39mil	3.5	
1	Тор	Copper	1.38mil		
	Dielectric 1	PP-006	4.80mil	4.2	
2	GND	Copper	1.38mil		
	Dielectric 2	Core-009	45.28mil	4.2	
3	PWR	Copper	1.38mil		
	Dielectric 3	PP-006	4.80mil	4.2	
1	Bottom	Copper	1.38mil		
	Bottom Solder	Solder Resist	O.39mil	3.5	
	Bottom Overlay				
	///////////////////////////////////////		'	'	



LAYER 4: BOTTOM BOTTOM SOLDERMASK

FRAME SIZE - 420 x 520 mm



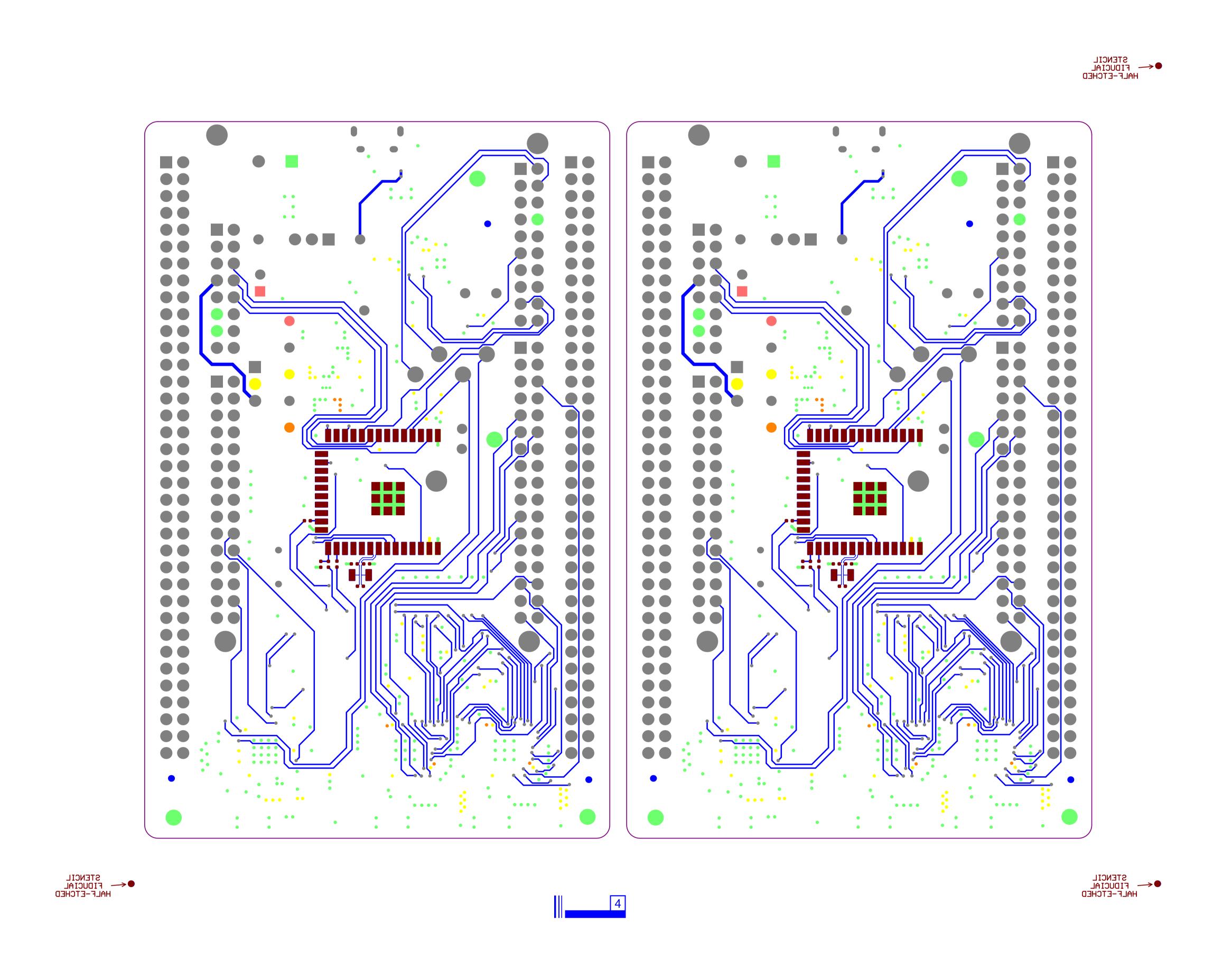
LAYER 1: TOP

BOARD OUTLINE

TOP PASTEMASK

Layer	Name	Material	Thickness	Constant	Board Layer Stac
	Top Overlay				
	Top Solder	Solder Resist	0.39mil	3.5	
	Тор	Copper	1.38mil		
	Dielectric 1	PP-006	4.80mil	4.2	
2	GND	Copper	1.38mil		
	Dielectric 2	Core-009	45.28mil	4.2	
	PWR	Copper	1.38mil		
	Dielectric 3	PP-006	4.80mil	4.2	
	Bottom	Copper	1.38mil		
	Bottom Solder	Solder Resist	O.39mil	3.5	
	Bottom Overlay				

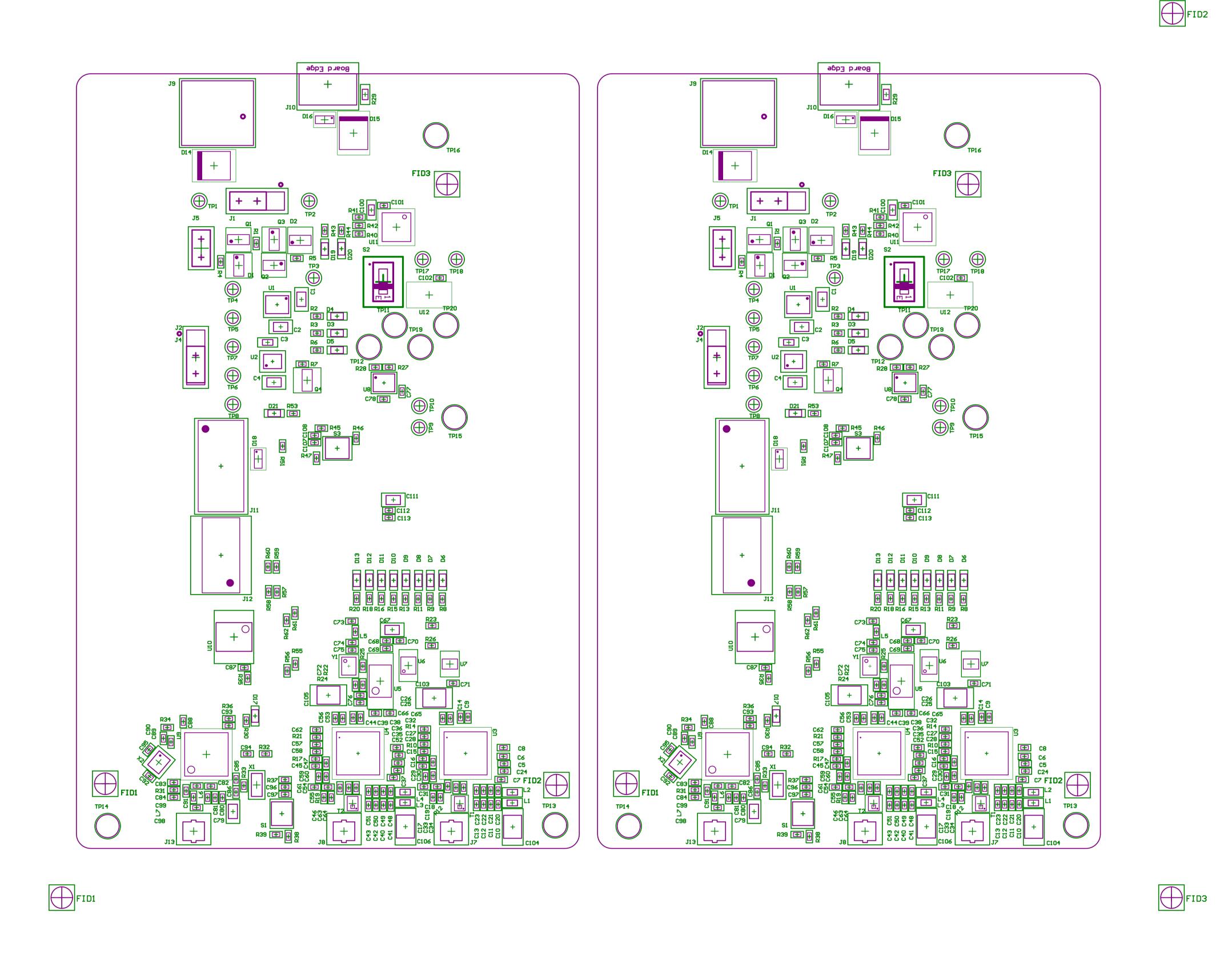
STENCIL THICKNESS - 0.1 MM



LAYER 4: BOTTOM

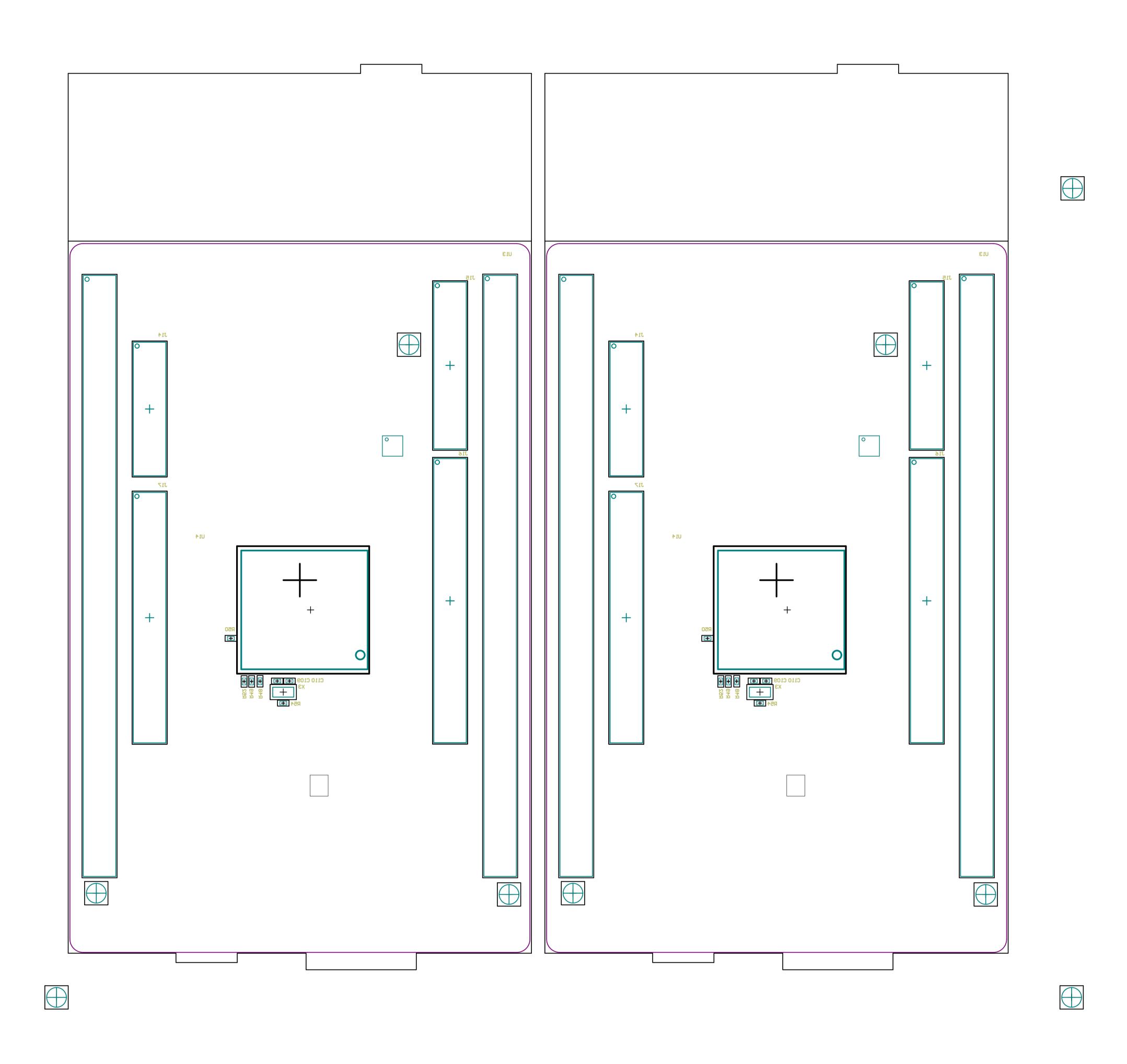
BOARD OUTLINE

BOTTOM PASTEMASK



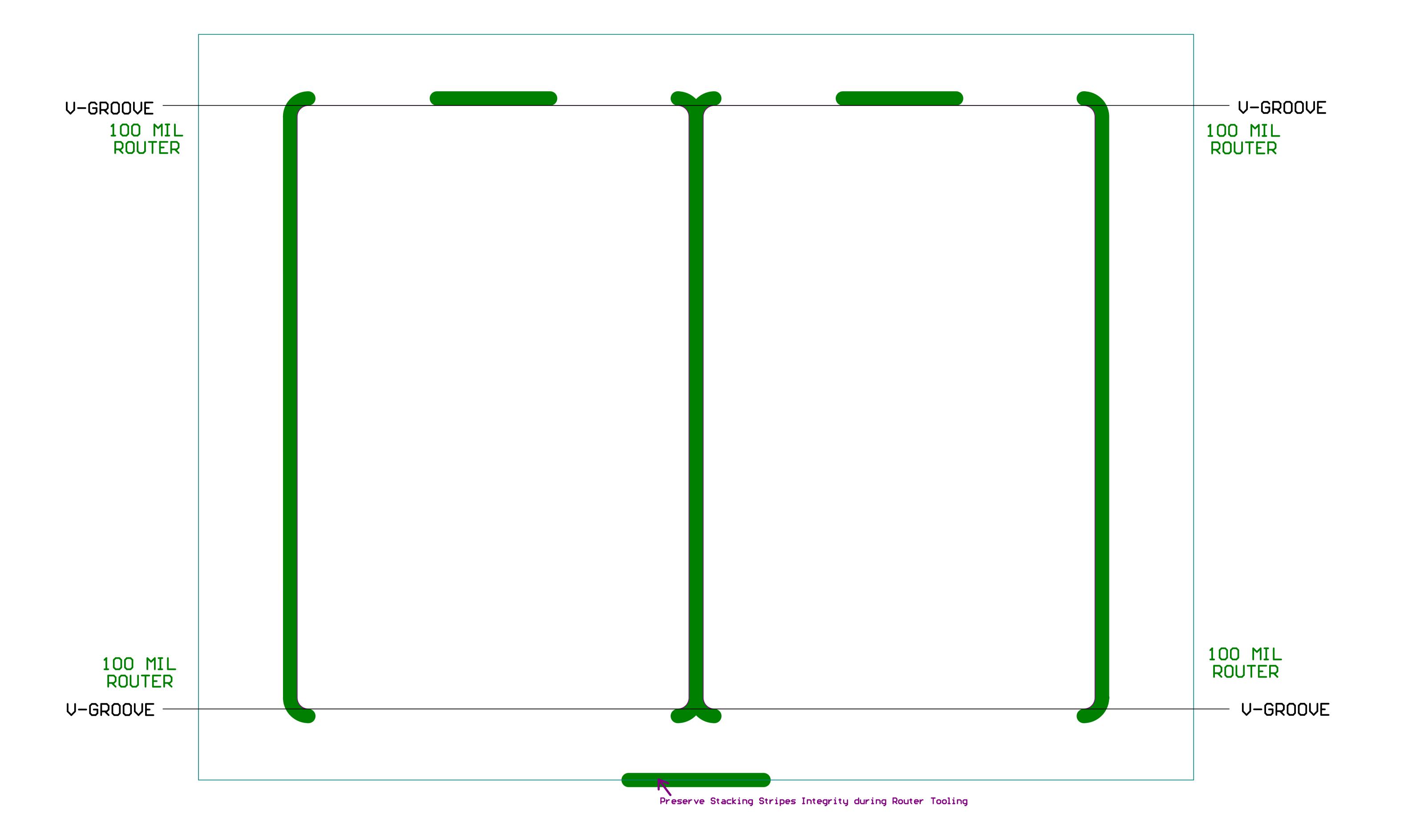
BOARD OUTLINE

TOP ASSEMBLY
TOP DESIGNATORS
TOP COURTYARD



BOARD OUTLINE

BOTTOM ASSEMBLY
BOTTOM COURTYARD
BOTTOM DESIGNATORS



BOARD OUTLINE
PANEL OUTLINE
ROUTE TOOL PATH
PANEL V-GROOVE

MANUFACTURING NOTES